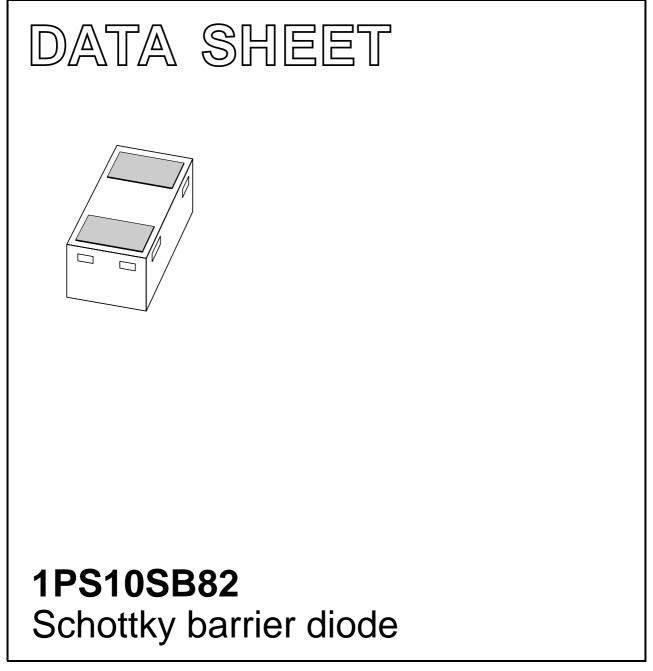
# DISCRETE SEMICONDUCTORS



Product data sheet

2003 Aug 20



## 1PS10SB82

## FEATURES

- Low forward voltage
- Low diode capacitance
- Leadless ultra small plastic package (1.0 mm × 0.6 mm × 0.5 mm)
- Boardspace 1.17 mm<sup>2</sup> (approx. 10% of SOT23)
- Power dissipation comparable to SOT23.

## APPLICATIONS

- UHF mixers
- Sampling circuits
- Modulators
- Phase detectors
- Mobile communication, digital (still) cameras, PDA's and PCMCIA cards.

## LIMITING VALUES

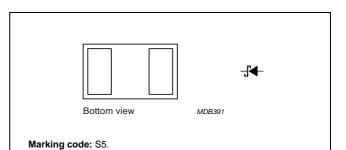
In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER		MAX.	UNIT
V <sub>R</sub>	continuous reverse voltage		15	V
I <sub>F</sub>	continuous forward current		30	mA
T <sub>stg</sub>	storage temperature		+150	°C
Tj	junction temperature		150	°C

## DESCRIPTION

An epitaxial Schottky barrier diode encapsulated in a SOD882 leadless ultra small plastic package.

ESD sensitive device, observe handling precautions.



The marking bar indicates the cathode.

Fig.1 Simplified outline (SOD882), pin configuration and symbol.

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## ELECTRICAL CHARACTERISTICS

 $T_{amb} = 25 \ ^{\circ}C$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V <sub>F</sub>	forward voltage	see Fig.2			
		I <sub>F</sub> = 1 mA	-	340	mV
		I <sub>F</sub> = 30 mA	-	700	mV
r <sub>D</sub>	differential diode forward resistance	$f = 1 MHz; I_F = 5 mA; see Fig.5$	12	-	Ω
I <sub>R</sub>	continuous reverse current	V <sub>R</sub> = 1 V; see Fig.3; note 1	-	0.2	μA
C <sub>d</sub>	diode capacitance	$V_R = 0 V$ ; f = 1 MHz; see Fig.4	1	-	pF

#### Note

1. Pulse test:  $t_p = 300 \ \mu s$ ;  $\delta = 0.02$ .

## THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-a</sub>	thermal resistance from junction to ambient	note 1	500	K/W

#### Note

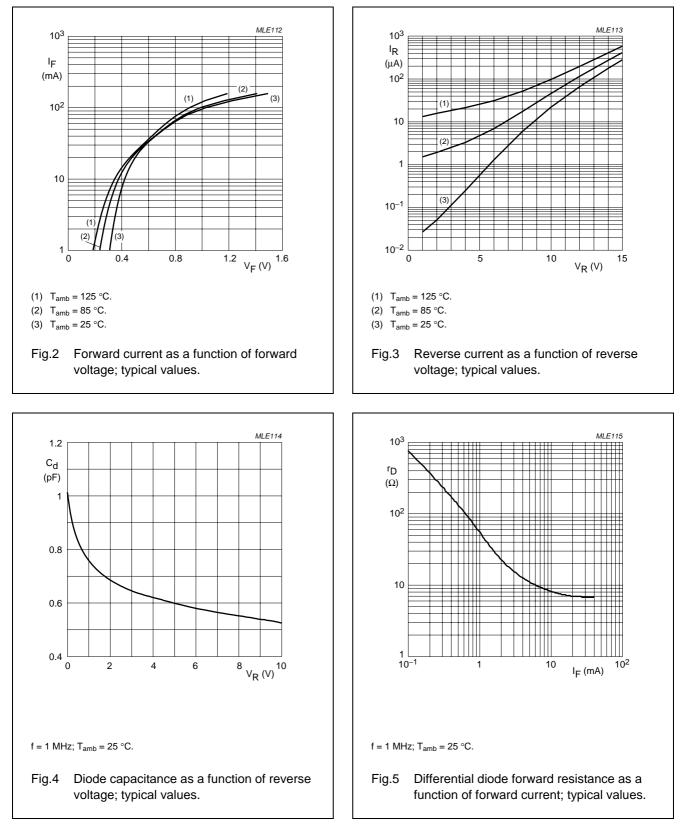
1. Refer to SOD882 standard mounting conditions (footprint), FR4 with 60  $\mu$ m copper strip line.

## Soldering

Reflow soldering is the only recommended soldering method.

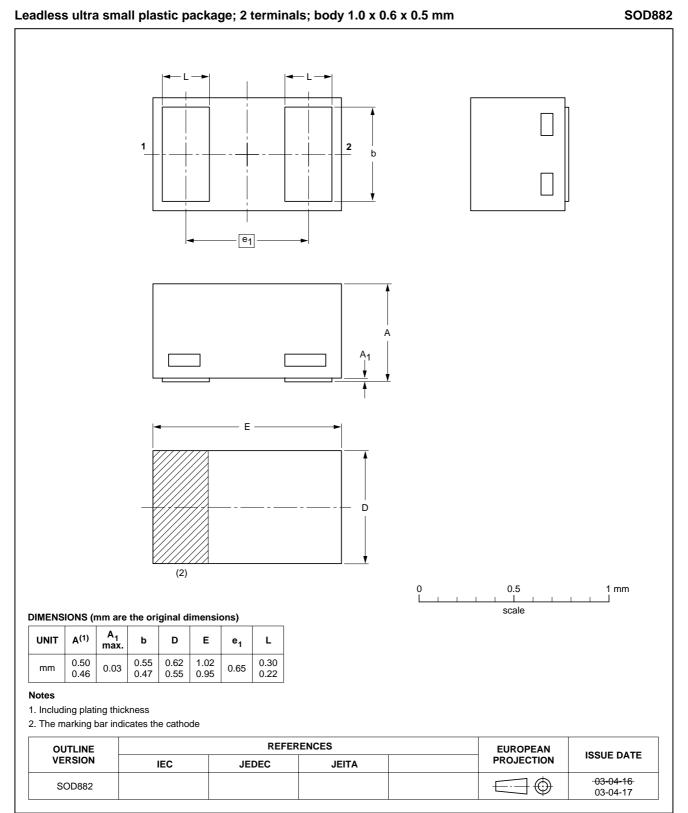
## 1PS10SB82





## 1PS10SB82

## PACKAGE OUTLINE



1PS10SB82

### DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

#### Notes

- 1. Please consult the most recently issued document before initiating or completing a design.
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